Renesas Electronics America Inc - IDT79RC32T355-150DHI Datasheet

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Applications of Embedded - Microprocessors

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details	
Product Status	Obsolete
Core Processor	MIPS-II
Number of Cores/Bus Width	1 Core, 32-Bit
Speed	150MHz
Co-Processors/DSP	-
RAM Controllers	SDRAM
Graphics Acceleration	No
Display & Interface Controllers	-
Ethernet	10/100Mbps (1)
SATA	-
USB	USB 1.1 (1)
Voltage - I/O	2.5V, 3.3V
Operating Temperature	-40°C ~ 85°C (TA)
Security Features	-
Package / Case	208-BFQFP
Supplier Device Package	208-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/idt79rc32t355-150dhi

- **USB**
  - *Revision 1.1 compliant*
  - *USB slave device controller*
  - *Supports a 6th USB endpoint*
  - *Full speed operation at 12 Mb/s*
  - *Supports control, interrupt, bulk and isochronous endpoints*
  - *Supports USB remote wakeup*
  - *Integrated USB transceiver*
- **TDM**
  - *Serial Time Division Multiplexed (TDM) voice and data interface*
  - *Provides interface to telephone CODECs and DSPs*
  - *Interface to high quality audio A/Ds and D/As with external glue logic*
  - *Support 1 to 128 8-bit time slots*
  - *Compatible with Lucent CHI, GCI, Mitel ST-bus, K2 and SLD busses*
  - *Supports data rates of up to 8.192 Mb/s*
  - *Supports internal or external frame generation*
  - *Supports multiple non-contiguous active input and output time slots*
- **EJTAG**
  - *Run-time Mode provides a standard JTAG interface*
  - *Real-Time Mode provides additional pins for real-time trace information*
- **Ethernet**
  - *Full duplex support for 10 and 100 Mb/s Ethernet*
  - *IEEE 802.3u compatible Media Independent Interface (MII) with serial management interface*
  - *IEEE 802.3u auto-negotiation for automatic speed selection*
  - *Flexible address filtering modes*
  - *64-entry hash table based multicast address filtering*
- **ATM SAR**
  - *Can be configured as one UTOPIA level 1 interface or 1 UTOPIA level 2 interface with 2 address lines (3 PHYs max)*
  - *Supports 25Mb/s and faster ATM*
  - *Supports UTOPIA data path interface operation at speeds up to 33 MHz*
  - *Supports standard 53-byte ATM cells*
  - *Performs HEC generation and checking*
  - *Cell processing discards short cells and clips long cells*
  - *16 cells worth of buffering*
  - *UTOPIA modes: 8 cell input buffer and 8 cell output buffer*
  - *Hardware support for CRC-32 generation and checking for AAL5*
  - *Hardware support for CRC-10 generation and checking*
  - *Virtual caching receive mechanism supports reception of any length packet without CPU intervention on up to eight simultaneously active receive channels*
  - *Frame Mode transmit mechanism supports transmission of any length packet without CPU intervention*
- **System Features**
  - *JTAG Interface (IEEE Std. 1149.1 compatible)*
  - *208 pin PQFP package*
  - *2.5V core supply and 3.3V I/O supply*
  - *Up to 180 MHz pipeline frequency and up to 75 MHz bus frequency*

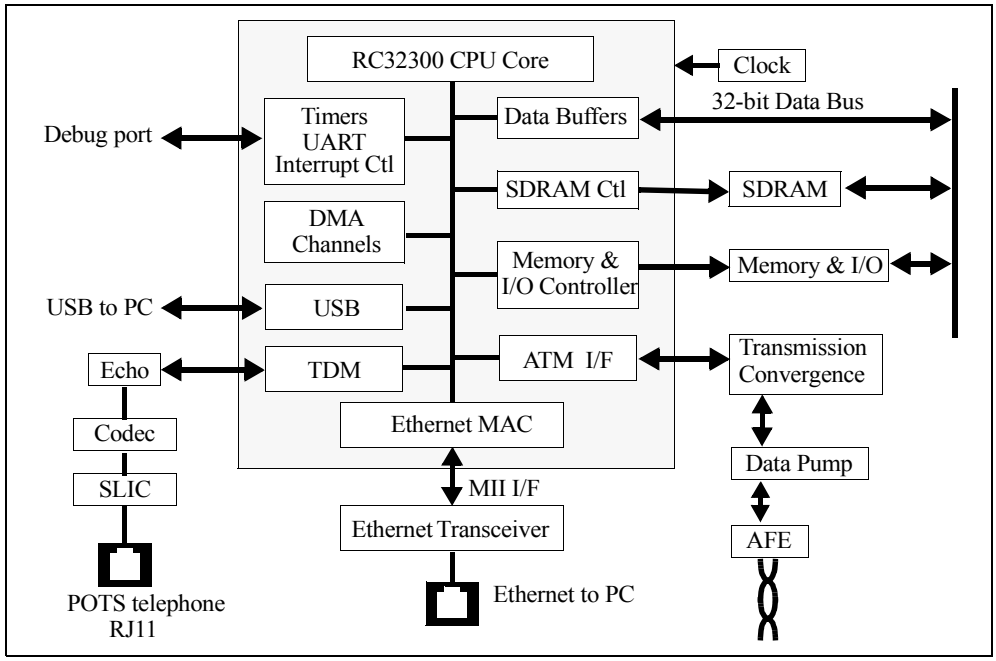


Figure 2 Example of xDSL Residential Gateway Using RC32355

Thermal Considerations

The RC32355 consumes less than 2.5 W peak power. It is guaranteed in a ambient temperature range of 0° to +70° C for commercial temperature devices and - 40° to +85° for industrial temperature devices.

Revision History

March 29, 2001: Initial publication.

September 24, 2001: Removed references to DPI interface. Removed references to “edge-triggered interrupt input” for GPIO pins. Changed 208-pin package designation from DP to DH.

October 10, 2001: Revised AC timing characteristics in Tables 5, 6, 7, 8, 10, 12, and 15. Revised values in Table 18, “DC Electrical Characteristics”; Table 20, “RC32355 Power Consumption”; and Figure 23, “Typical Power Usage.” Changed data sheet from Preliminary to Final.

October 23, 2001: Revised Figure 23, “Typical Power Usage.”

November 1, 2001: Added Input Voltage Undershoot parameter and a footnote to Table 21.

January 30, 2002: In Table 6, changed values from 1.5 to 1.2 for the following signals: MDATA Tdo1, MADDR Tdo2, CASN Tdo3, CKENP Tdo4, BDIRN Tdo5, BOEN Tdo6.

May 20, 2002: Changed values in Table 20, Power Consumption.

September 19, 2002: Added COLDRSTN Trise1 parameter to Table 5, Reset and System AC Timing Characteristics.

December 6, 2002: In Features section, changed UART speed from 115 Kb/s to 1.5 Mb/s.

December 17, 2002: Added V_{OH} parameter to Table 18, DC Electrical Characteristics.

January 27, 2004: Added 180MHz speed grade.

May 25, 2004: In Table 7, signals MIIRXCLK and MIITXCLK, the Min and Max values for 10 Mbps Thigh1/Tlow1 were changed to 140 and 260 respectively and the Min and Max values for 100 Mbps Thigh1/Tlow1 were changed to 14.0 and 26.0 respectively.

Pin Description Table

The following table lists the functions of the pins provided on the RC32355. Some of the functions listed may be multiplexed onto the same pin.

To define the active polarity of a signal, a suffix will be used. Signals ending with an "N" should be interpreted as being active, or asserted, when at a logic zero (low) level. All other signals (including clocks, buses and select lines) will be interpreted as being active, or asserted when at a logic one (high) level.

Note: The input pads of the RC32355 do not contain internal pull-ups or pull-downs. Unused inputs should be tied off to appropriate levels. This is especially critical for unused control signal inputs (such as BRN) which, if left floating, could adversely affect the RC32355's operation. Also, any input pin left floating can cause a slight increase in power consumption.

Name	Type	I/O Type	Description
System			
CLKP	I	Input	**System Clock input.** This is the system master clock input. The RISCore 32300 pipeline frequency is a multiple (x2, x3, or x4) of this clock frequency. All other logic runs at this frequency or less.
COLDRSTN	I	STI[1]	**Cold Reset.** The assertion of this signal low initiates a cold reset. This causes the RC32355 state to be initialized, boot configuration to be loaded, and the internal processor PLL to lock onto the system clock (CLKP).
RSTN	I/O	Low Drive with STI	**Reset.** This bidirectional signal is either driven low or tri-stated, an external pull-up is required to supply the high state. The RC32355 drives RSTN low during a reset (to inform the external system that a reset is taking place) and then tri-states it. The external system can drive RSTN low to initiate a warm reset, and then should tri-state it.
SYSCLKP	O	High Drive	**System clock output.** This is a buffered and delayed version of the system clock input (CLKP). All SDRAM transactions are synchronous to this clock. This pin should be externally connected to the SDRAMs and to the RC32355 SDCLKINP pin (SDRAM clock input).
Memory and Peripheral Bus			
MADDR[25:0]	O	[21:0] High Drive [25:22] Low Drive with STI	**Memory Address Bus.** 26-bit address bus for memory and peripheral accesses. MADDR[20:17] are used for the SODIMM data mask enables if SODIMM mode is selected. MADDR[22] Primary function: General Purpose I/O, GPIOP[27]. MADDR[23] Primary function: General Purpose I/O, GPIOP[28]. MADDR[24] Primary function: General Purpose I/O, GPIOP[29]. MADDR[25] Primary function: General Purpose I/O, GPIOP[30].
MDATA[31:0]	I/O	High Drive	**Memory Data Bus.** 32-bit data bus for memory and peripheral accesses.
BDIRN	O	High Drive	**External Buffer Direction.** External transceiver direction control for the memory and peripheral data bus, MDATA[31:0]. It is asserted low during any read transaction, and remains high during write transactions.
BOEN[1:0]	O	High Drive	**External Buffer Output Enable.** These signals provide two output enable controls for external data bus transceivers on the memory and peripheral data bus, MDATA. BOEN[0] is asserted low during external device read transactions. BOEN[1] is asserted low during SDRAM read transactions.
BRN	I	STI	**External Bus Request.** This signal is asserted low by an external master device to request ownership of the memory and peripheral bus.
BGN	O	Low Drive	**External Bus Grant.** This signal is asserted low by RC32355 to indicate that RC32355 has relinquished ownership of the local memory and peripheral bus to an external master.
WAITACKN	I	STI	**Wait or Transfer Acknowledge.** When configured as wait, this signal is asserted low during a memory and peripheral device bus transaction to extend the bus cycle. When configured as transfer acknowledge, this signal is asserted low during a memory and peripheral device bus transaction to signal the completion of the transaction.
CSN[5:0]	O	[3:0] High Drive [5:4] Low Drive	**Device Chip Select.** These signals are used to select an external device on the memory and peripheral bus during device transactions. Each bit is asserted low during an access to the selected external device. CSN[4] Primary function: General purpose I/O, GPIOP[16]. CSN[5] Primary function: General purpose I/O, GPIOP[17].

Table 1 Pin Descriptions (Part 1 of 8)

Name	Type	I/O Type	Description
RWN	O	High Drive	**Read or Write.** This signal indicates if the transaction on the memory and peripheral bus is a read transaction or a write transaction. A high level indicates a read from an external device, a low level indicates a write to an external device.
OEN	O	High Drive	**Output Enable.** This signal is asserted low when data should be driven by an external device during device read transactions on the memory and peripheral bus.
BWEN[3:0]	O	High Drive	**SDRAM Byte Enable Mask or Memory and I/O Byte Write Enables.** These signals are used as data input/output masks during SDRAM transactions and as byte write enable signals during device controller transactions on the memory and peripheral bus. They are active low. BWEN[0] corresponds to byte lane MDATA[7:0]. BWEN[1] corresponds to byte lane MDATA[15:8]. BWEN[2] corresponds to byte lane MDATA[23:16]. BWEN[3] corresponds to byte lane MDATA[31:24].
SDCSN[1:0]	O	High Drive	**SDRAM Chip Select.** These signals are used to select the SDRAM device on the memory and peripheral bus. Each bit is asserted low during an access to the selected SDRAM.
RASN	O	High Drive	**SDRAM Row Address Strobe**. The row address strobe asserted low during memory and peripheral bus SDRAM transactions.
CASN	O	High Drive	**SDRAM Column Address Strobe.** The column address strobe asserted low during memory and peripheral bus SDRAM transactions.
SDWEN	O	High Drive	**SDRAM Write Enable.** Asserted low during memory and peripheral bus SDRAM write transactions.
CKENP	O	Low Drive	**SDRAM Clock Enable.** Asserted high during active SDRAM clock cycles. Primary function: General Purpose I/O, GPIOP[21].
SDCLKINP	I	STI	**SDRAM Clock Input.** This clock input is a delayed version of SYSCLKP. SDRAM read data is sampled into the RC32355 on the rising edge of this clock.
ATM Interface			
ATMINP[11:0]	I	STI	**ATM PHY Inputs.** These pins are the inputs for the ATM interface.
ATMIOP[1:0]	I/O	Low Drive with STI	**ATM PHY Bidirectional Signals.** These pins are the bidirectional pins for the ATM interface.
ATMOUTP[9:0]	O	Low Drive	**ATM PHY Outputs.** These pins are the outputs for the ATM interface.
TXADDR[1:0]	O	Low Drive	**ATM Transmit Address [1:0]**. 2-bit address bus used for transmission in Utopia-2 mode. TXADDR[0] Primary function: General purpose I/O, GPIOP[22]. TXADDR[1] Primary function: General purpose I/O, GPIOP[23].
RXADDR[1:0]	O	Low Drive	**ATM Receive Address [1:0]**. 2-bit address bus for receiving in Utopia-2 mode. RXADDR[0] Primary function: General purpose I/O, GPIOP[24]. RXADDR[1] Primary function: General purpose I/O, GPIOP[25].
TDM Bus			
TDMDOP	O	High Drive	**TDM Serial Data Output.** Serial data is driven by the RC32355 on this signal during an active output time slot. During inactive time slots this signal is tri-stated. Primary function: General purpose I/O, GPIOP[32].
TDMDIP	I	STI	**TDM Serial Data Input.** Serial data is received by the RC32355 on this signal during active input time slots. Primary function: General purpose I/O, GPIOP[33].
TDMFP	I/O	High Drive	**TDM Frame Signal.** A transition on this signal, the active polarity of which is programmable, delineates the start of a new TDM bus frame. TDMFP is driven if the RC32355 is a master, and is received if it is a slave. Primary function: General purpose I/O, GPIOP[34].
TDMCLKP	I	STI	**TDM Clock.** This input clock controls the rate at which data is sent and received on the TDM bus. Primary function: General purpose I/O, GPIOP[35].

Table 1 Pin Descriptions (Part 2 of 8)

Name	Type	I/O Type	Description
DMAREQN	I	STI	**External DMA Device Request**. The external DMA device asserts this pin low to request DMA service. Primary function: General purpose I/O, GPIOP[18]. At reset, this pin defaults to primary function GPIOP[18].
DMADONEN	I	STI	**External DMA Device Done**. The external DMA device asserts this signal low to inform the RC32355 that it is done with the current DMA transaction. Primary function: General purpose I/O, GPIOP[19]. At reset, this pin defaults to primary function GPIOP[19].
USB			
USBCLKP	I	STI	**USB Clock.** 48 MHz clock input used as time base for the USB interface.
USBDN	I/O	USB	**USB D- Data Line.** This is the negative differential USB data signal.
USBDP	I/O	USB	**USB D+ Data Line.** This is the positive differential USB data signal.
USBSOF	O	Low Drive	**USB start of frame.** Primary function: General Purpose I/O, GPIOP[20]. At reset, this pin defaults to primary function GPIOP[20].
Ethernet			
MIICOLP	I	STI	**MII Collision Detected.** This signal is asserted by the ethernet PHY when a collision is detected.
MIICRSP	I	STI	**MII Carrier Sense.** This signal is asserted by the ethernet PHY when either the transmit or receive medium is not idle.
MIIMDCP	O	Low Drive	**MII Management Data Clock.** This signal is used as a timing reference for transmission of data on the management interface.
MIIMDIOP	I/O	Low Drive with STI	**MII Management Data.** This bidirectional signal is used to transfer data between the station management entity and the ethernet PHY.
MIIRXCLKP	I	STI	**MII Receive Clock.** This clock is a continuous clock that provides a timing reference for the reception of data.
MIIRXDP[3:0]	I	STI	**MII Receive Data.** This nibble wide data bus contains the data received by the ethernet PHY.
MIIRXDVP	I	STI	**MII Receive Data Valid.** The assertion of this signal indicates that valid receive data is in the MII receive data bus.
MIIRXERP	I	STI	**MII Receive Error.** The assertion of this signal indicates that an error was detected somewhere in the ethernet frame currently being sent in the MII receive data bus.
MIITXCLKP	I	STI	**MII Transmit Clock.** This clock is a continuous clock that provides a timing reference for the transfer of transmit data.
MIITXDP[3:0]	O	Low Drive	**MII Transmit Data.** This nibble wide data bus contains the data to be transmitted.
MIITXENP	O	Low Drive	**MII Transmit Enable.** The assertion of this signal indicates that data is present on the MII for transmission.
MIITXERP	O	Low Drive	**MII Transmit Coding Error.** When this signal is asserted together with MIITXENP, the ethernet PHY will transmit symbols which are not valid data or delimiters.
I^2C			
SCLP	I/O	Low Drive with STI	**I^2C Interface Clock**. An external pull-up is required on SCLP, see the I^2C spec.[2] Primary function: General purpose I/O, GPIOP[15]. At reset, this pin defaults to primary function GPIOP[15].
SDAP	I/O	Low Drive with STI	**I^2C Interface Data Pin.** An external pull-up is required on SDAP, see the I^2C spec.[2] Primary function: General purpose I/O, GPIOP[14]. At reset, this pin defaults to primary function GPIOP[14].
EJTAG			
JTAG_TCK	I	STI	**JTAG Clock.** This is an input test clock, used to shift data into or out of the boundary scan logic. This signal requires an external resistor, listed in Table 16.
JTAG_TDI	I	STI	**JTAG Data Input.** This is the serial data shifted into the boundary scan logic. This signal requires an external resistor, listed in Table 16. This is also used to input EJTAG_DINTN during EJTAG/ICE mode. EJTAG_DINTN is an interrupt to switch the PC trace mode off.
JTAG_TDO	O	Low Drive	**JTAG Data Output.** This is the serial data shifted out from the boundary scan logic. When no data is being shifted out, this signal is tri-stated. This signal requires an external resistor, listed in Table 16. This is also used to output the EJTAG_TPC during EJTAG/ICE mode. EJTAG_TPC is the non-sequential program counter output.

Table 1 Pin Descriptions (Part 5 of 8)

Name	Type	I/O Type	Description
JTAG_TMS	I	STI	**JTAG Mode Select**. This input signal is decoded by the tap controller to control test operation. This signal requires an external resistor, listed in Table 16.
EJTAG_PCST[0]	O	Low Drive	**PC trace status.** This bus gives the PC trace status information during EJTAG/ICE mode. EJTAG/ICE enable is selected during reset using the boot configuration and overrides the selection of the Primary and Alternate functions. This signal requires an external resistor, listed in Table 16. Primary function: General Purpose I/O, GPIOP[10]. 1st Alternate function: UART channel 1 data terminal ready, U1DTRN.
EJTAG_PCST[1]	O	Low Drive	**PC trace status.** This bus gives the PC trace status information during EJTAG/ICE mode. EJTAG/ICE enable is selected during reset using the boot configuration and overrides the selection of the Primary and Alternate functions. This signal requires an external resistor, listed in Table 16. Primary function: General Purpose I/O, GPIOP[11]. At reset, this pin defaults to primary function GPIOP[11]. 1st Alternate function: UART channel 1 data set ready, U1DSRN.
EJTAG_PCST[2]	O	Low Drive	**PC trace status.** This bus gives the PC trace status information during EJTAG/ICE mode. EJTAG/ICE enable is selected during reset using the boot configuration and overrides the selection of the Primary and Alternate functions. This signal requires an external resistor, listed in Table 16. Primary function: General Purpose I/O, GPIOP[12]. 1st Alternate function: UART channel 1 request to send, U1RTSN.
EJTAG_DCLK	O	Low Drive	**PC trace clock.** This is used to capture address and data during EJTAG/ICE mode. EJTAG/ICE enable is selected during reset using the boot configuration and overrides the selection of the Primary and Alternate functions. This signal requires an external resistor, listed in Table 16. Primary function: General Purpose I/O, GPIOP[13]. 1st Alternate function: UART channel 1 clear to send, U1CTSN.
EJTAG_TRST_N	I	STI	**EJTAG Test Reset.** EJTAG_TRST_N is an active-low signal for asynchronous reset of only the EJTAG/ICE controller. EJTAG_TRST_N requires an external pull-up on the board. EJTAG/ICE enable is selected during reset using the boot configuration and overrides the selection of the Primary and Alternate functions. This signal requires an external resistor, listed in Table 16. Primary: General Purpose I/O, GPIOP[31] 1st Alternate function: DMA finished output, DMAFIN.
JTAG_TRST_N	I	STI	**JTAG Test Reset.** JTAG_TRST_N is an active-low signal for asynchronous reset of only the JTAG boundary scan controller. JTAG_TRST_N requires an external pull-down on the board that will hold the JTAG boundary scan controller in reset when not in use if selected. JTAG reset enable is selected during reset using the boot configuration and overrides the selection of the Primary and Alternate functions. Primary function: General Purpose I/O, GPIOP[2]. 1st Alternate function: UART channel 0 ring indicator, U0RIN.
Debug			
INSTP	O	Low Drive	**Instruction or Data Indicator**. This signal is driven high during CPU instruction fetches and low during CPU data transactions on the memory and peripheral bus.
CPUP	O	Low Drive	**CPU or DMA Transaction Indicator**. This signal is driven high during CPU transactions and low during DMA transactions on the memory and peripheral bus if CPU/DMA Transaction Indicator Enable is enabled. CPU/DMA Status mode enable is selected during reset using the boot configuration and overrides the selection of the Primary and Alternate functions. Primary function: General Purpose I/O, GPIOP[4]. 1st Alternate function: UART channel 0 data terminal ready U0DTRN.
DMAP[0]	O	Low Drive	**Active DMA channel code**. DMA debug enable is selected during reset using the boot configuration and overrides the selection of the Primary and Alternate functions. Primary function: General Purpose I/O, GPIOP[23]. 1st Alternate function: TXADDR[1].
DMAP[1]	O	Low Drive	**Active DMA channel code**. DMA debug enable is selected during reset using the boot configuration and overrides the selection of the Primary and Alternate functions. Primary function: General Purpose I/O, GPIOP[25]. 1st Alternate function: RXADDR[1].

Table 1 Pin Descriptions (Part 6 of 8)

Name	Type	I/O Type	Description
U1CTSN	I	STI	**UART channel 1 clear to send.** Primary function: General Purpose I/O, GPIOP[13]. At reset, this pin defaults to primary function GPIOP[13] if ICE Interface enable is not selected during reset using the boot configuration. 2nd Alternate function: PC trace clock, EJTAG_DCLK.

Table 1 Pin Descriptions (Part 8 of 8)

1. Schmitt Trigger Input.
2. 2I^2C - Bus Specification by Philips Semiconductors.

Boot Configuration Vector

The boot configuration vector is read into the RC32355 during cold reset. The vector defines parameters in the RC32355 that are essential to operation when cold reset is complete.

The encoding of boot configuration vector is described in Table 2, and the vector input is illustrated in Figure 6.

Signal	Name/Description
MDATA[2:0]	**Clock Multiplier**. This field specifies the value by which the system clock (CLKP) is multiplied internally to generate the CPU pipeline clock. 0x0 - multiply by 2 0x1 - multiply by 3 0x2 - multiply by 4 0x3 - reserved 0x4 - reserved 0x5 - reserved 0x6 - reserved 0x7 - reserved
MDATA[3]	**Endian.** This bit specifies the endianness of RC32355. 0x0 - little endian 0x1 - big endian
MDATA[4]	**Reserved.** Must be set to 0.
MDATA[5]	**Debug Boot Mode**. When this bit is set, the RC32355 begins executing from address 0xFF20_0200 rather than 0xBFC0_0000 following a reset. 0x0 - regular mode (processor begins executing at 0xBFC0_0000) 0x1 - debug boot mode (processor begins executing at 0xFF20_0200)
MDATA[7:6]	**Boot Device Width**. This field specifies the width of the boot device. 0x0 - 8-bit boot device width 0x1 - 16-bit boot device width 0x2 - 32-bit boot device width 0x3 - reserved
MDATA[8]	**EJTAG/ICE Interface Enable**. When this bit is set, Alternate 2 pin functions EJTAG_PCST[2:0], EJTAG_DCLK, and EJTAG_TRST_N are selected. 0x0 - GPIOP[31, 13:10] pins behaves as GPIOP 0x1 - GPIOP[31] pin behaves as EJTAG_TRST_N, GPIOP[12:10] pins behave as EJTAG_PCST[2:0], and GPIOP[13] pin behaves as EJTAG_DCLK
MDATA[9]	**Fast Reset**. When this bit is set, RC32355 drives RSTN for 64 clock cycles, used during test only. Clear this bit for normal operation. 0x0 - Normal reset: RC32355 drives RSTN for minimum of 4096 clock cycles 0x1 - Fast Reset: RC32355 drives RSTN for 64 clock cycles (test only)
MDATA[10]	**DMA Debug Enable**. When this bit is set, Alternate 2 pin function, DMAP is selected. DMAP provides the DMA channel number during memory and peripheral bus DMA transactions. 0x0 - GPIOP[8, 9, 25, 23] pins behave as GPIOP 0x1 - GPIOP[8, 9, 25, 23] pins behave as DMAP[3:0]

Table 2 Boot Configuration Vector Encoding (Part 1 of 2)

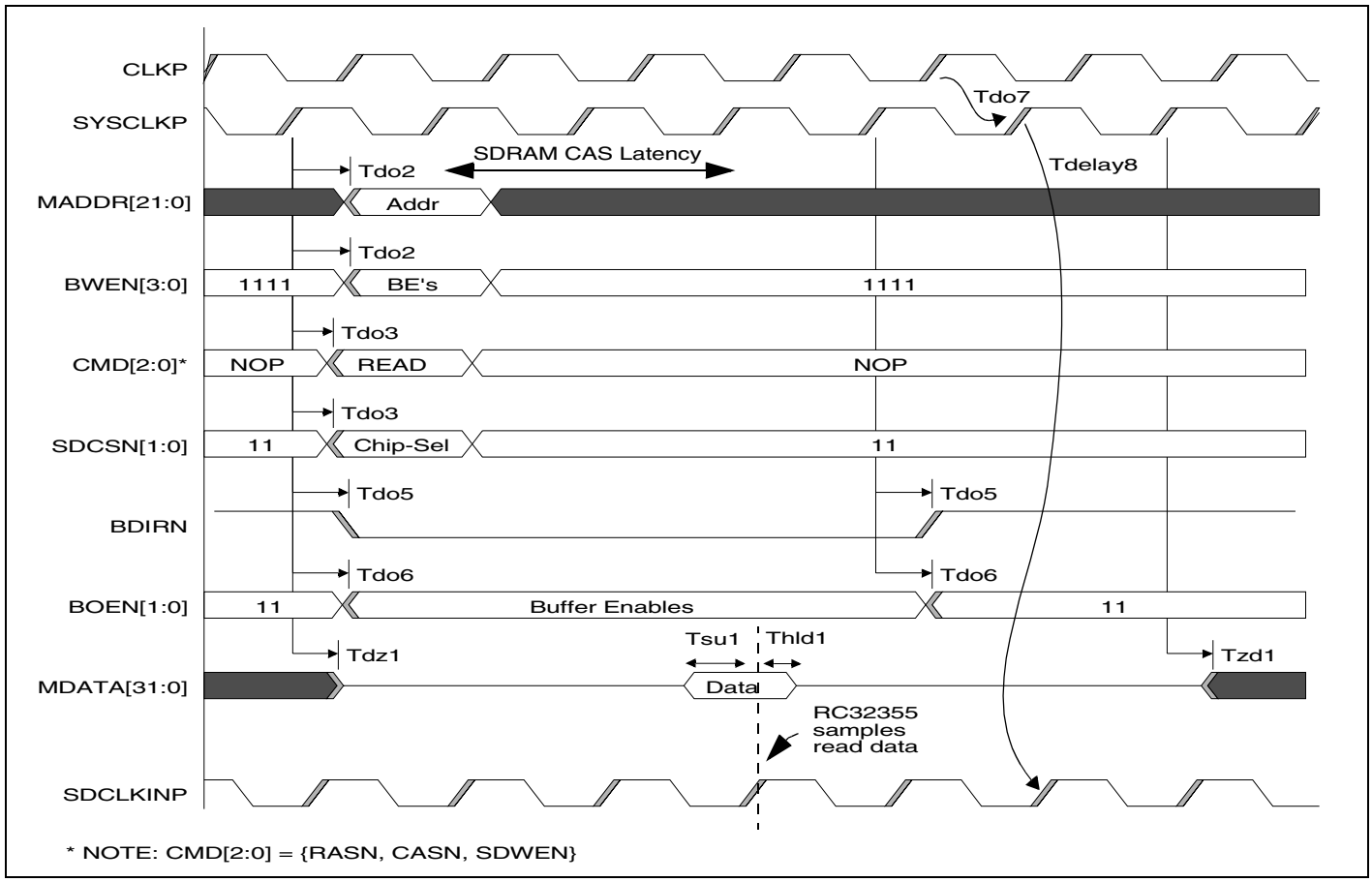


Figure 8 Memory and Peripheral Bus AC Timing Waveform - SDRAM Read Access

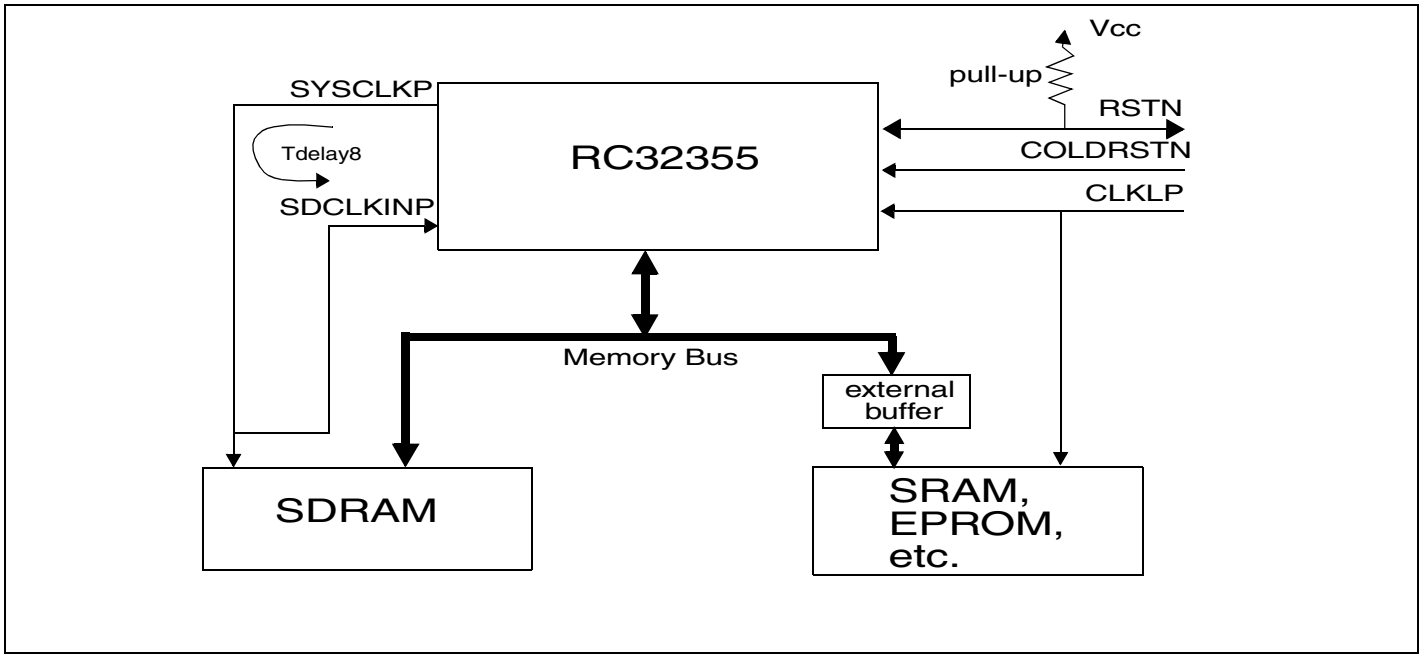


Figure 9 SYSCLKP - SDCLKINP Relationship

Signal	Symbol	Reference Edge	133MHz		150MHz		180MHz		Unit	Conditions	Timing Diagram Reference
			Min	Max	Min	Max	Min	Max			
Ethernet[1,2]											
MIIRXCLKP, MIITXCLKP	Tperiod1	none	399.96	400.04	399.96	400.04	399.96	400.04	ns	10 Mbps	Figure 13
	Thigh1,Tlow1		140	260	140	260	140	260	ns		
	Trise1,Tfall1		—	3	—	3	—	3	ns		
MIIRXCLKP, MIITXCLKP	Tperiod1	none	39.996	40.004	39.996	40.004	39.996	40.004	ns	100 Mbps	
	Thigh1,Tlow1		14	26	14	26	14	26	ns		
	Trise1,Tfall1		—	2	—	2	—	2	ns		
MIIRXDP[3:0], MIIRXDVP, MIIRXERP	Tsu2	MIIRXCLKP rising	5	—	5	—	5	—	ns		
	Thld2		3	—	3	—	3	—	ns		
MIITXDP[3:0], MIITXENP, MIITXERP	Tdo3	MIITXCLKP rising	7	13	7	13	7	13	ns		
MIIMDCP	Tperiod4	none	30	—	27	—	27	—	ns		
	Thigh4,Tlow4		14	—	13	—	13	—	ns		
	Trise4		—	11	—	11	—	11	ns		
	Tfall4		—	8	—	8	—	8	ns		
MIIMDIOP	Tsu5	MIIMDCP rising	6	—	6	—	6	—	ns		
	Thld5		0.5	—	0.5	—	0.5	—	ns		
	Tdo5		3	7	3	7	3	7	ns		

[1] Ethernet clock (MIIRXCLKP and MIITXCLKP) frequency must be equal to or less than 1/2 CLKP frequency.
[2] MIICOLP and MIICRSP are asynchronous signals.

Table 7 Ethernet AC Timing Characteristics

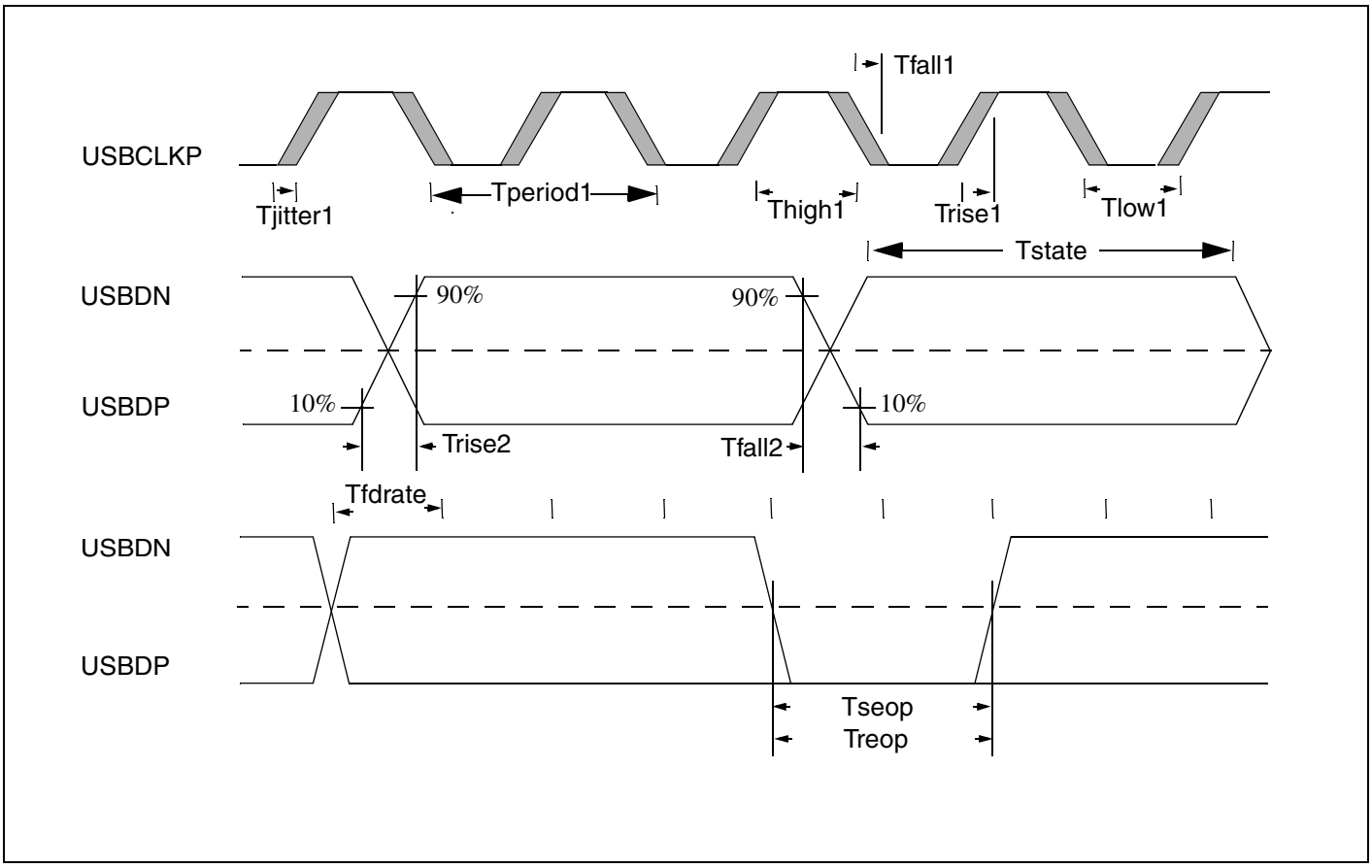


Figure 17 USB AC Timing Waveform

Signal	Symbol	Reference Edge	133MHz		150MHz		180MHz		Unit	Conditions	Timing Diagram Reference
			Min	Max	Min	Max	Min	Max			
UART											
U0SINP, U0RIN, U0DCDN, U0DSRN, U0CTSN, U1SINP, U1DSRN, U1CTSN	Tsu[1]	CLKP rising	5	—	5	—	5	—	ns		
	Thld[1]		3	—	3	—	3	—	ns		
U0SOUTP, U0DTRN, U0RTSN, U1SOUTP, U1DTRN, U1RTSN	Tdo[1]	CLKP rising	1	12	1	12	1	12	ns		
[1] These are asynchronous signals and the values are provided for ATE (test) only.											

Table 12 UART AC Timing Characteristics

Signal	Symbol	Reference Edge	133MHz		150MHz		180MHz		Unit	Conditions	Timing Diagram Reference
			Min	Max	Min	Max	Min	Max			
I^2C[1]											
SCLP	Frequency	none	0	100	0	100	0	100	kHz	100 KHz	Figure 18
	Thigh1		4.0	—	4.0	—	4.0	—	µs		
	Tlow1		4.7	—	4.7	—	4.7	—	µs		
	Trise1		—	1000	—	1000	—	1000	ns		
	Tfall1		—	300	—	300	—	300	ns		
SDAP	Tsu2	SCLP rising	250	—	250	—	250	—	ns		
	Thld2		0	3.45	0	3.45	0	3.45	µs		
	Trise2		—	1000	—	1000	—	1000	ns		
	Tfall2		—	300	—	300	—	300	ns		
Start or repeated start condition	Tsu3	SDAP falling	4.7	—	4.7	—	4.7	—	µs		
	Thld3		4.0	—	4.0	—	4.0	—	µs		
Stop condition	Tsu4	SDAP rising	4.0	—	4.0	—	4.0	—	µs		
Bus free time between a stop and start condition	Tdelay5		4.7	—	4.7	—	4.7	—	µs		
SCLP	Frequency	none	0	400	0	400	0	400	kHz	400 KHz	
	Thigh1		0.6	—	0.6	—	0.6	—	µs		
	Tlow1		1.3	—	1.3	—	1.3	—	µs		
	Trise1		—	300	—	300	—	300	ns		
	Tfall1		—	300	—	300	—	300	ns		
SDAP	Tsu2	SCLP rising	100	—	100	—	100	—	ns		
	Thld2		0	0.9	0	0.9	0	0.9	µs		
	Trise2		—	300	—	300	—	300	ns		
	Tfall2		—	300	—	300	—	300	ns		
Start or repeated start condition	Tsu3	SDAP falling	0.6	—	0.6	—	0.6	—	µs		
	Thld3		0.6	—	0.6	—	0.6	—	µs		
Stop condition	Tsu4	SDAP rising	0.6	—	0.6	—	0.6	—	µs		
Bus free time between a stop and start condition	Tdelay5		1.3	—	1.3	—	1.3	—	µs		

Table 13 I^2C AC Timing Characteristics

1. For more information see the I^2C-Bus specification by Philips Semiconductor

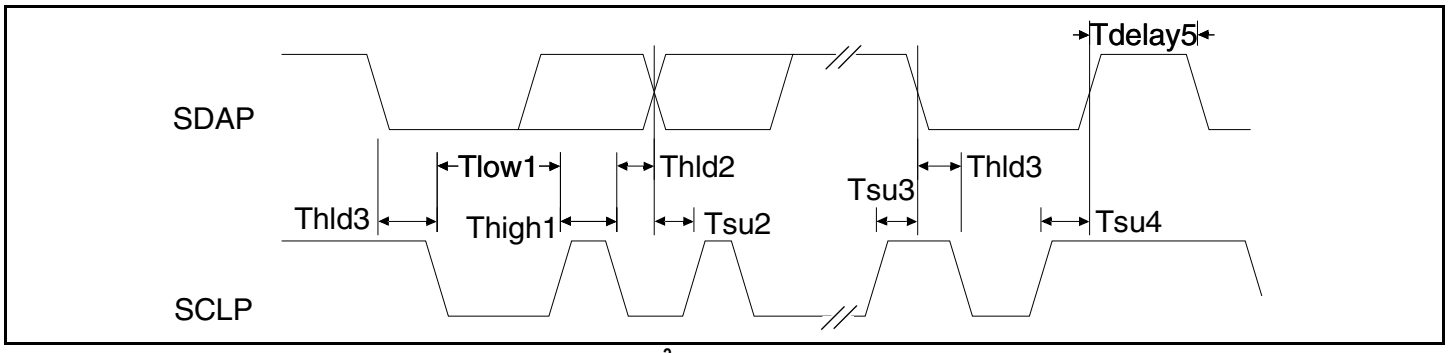


Figure 18 I^2C AC Timing Waveform

Signal	Symbol	Reference Edge	133MHz		150MHz		180MHz		Unit	Conditions	Timing Diagram Reference
			Min	Max	Min	Max	Min	Max			
GPIOP											
GPIOP[31:0][1]	Tsu1	CLKP rising	4	—	4	—	4	—	ns		Figure 19
	Thld1		1.4	—	1.4	—	1.4	—	ns		
	Tdo1		2	8	2	8	2	8	ns		
GPIOP[35:32][2]	Tsu1		3	—	3	—	3	—	ns		
	Thld1		1	—	1	—	1	—	ns		
	Tdo1		3	8	3	8	3	8	ns		

[1] GPIOP[31:0] are controlled through the GPIO interface. GPIO[31:0] are asynchronous signals, the values are provided for ATE (test) only.
[2] GPIOP[35:32] are controlled through the TDM interface.

Table 14 GPIOP AC Timing Characteristics

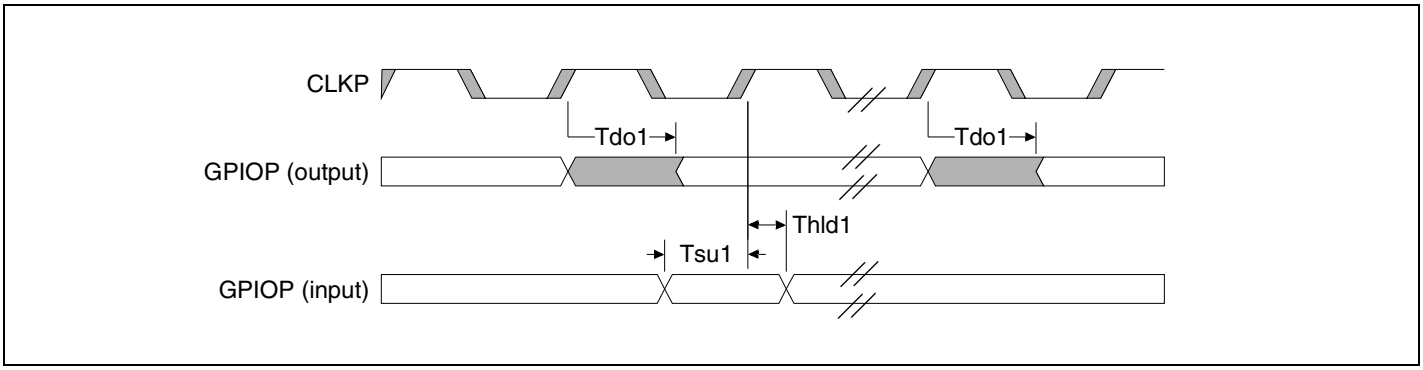


Figure 19 GPIOP AC Timing Waveform

Power-on RampUp

The 2.5V core supply (and 2.5V V_{cc}PLL supply) can be fully powered without the 3.3V I/O supply. However, the 3.3V I/O supply cannot exceed the 2.5V core supply by more than 1 volt during power up. A sustained large power difference could potentially damage the part. Inputs should not be driven until the part is fully powered. Specifically, the input high voltages should not be applied until the 3.3V I/O supply is powered.

There is no special requirement for how fast V_{cc} I/O ramps up to 3.3V. However, all timing references are based on a stable V_{cc} I/O.

DC Electrical Characteristics

($T_{ambient}$ = 0°C to +70°C Commercial, $T_{ambient}$ = -40°C to +85°C Industrial, Vcc I/O = +3.3V±5%, V_{cc} Core and V_{cc} P = +2.5V±5%)

	Para-meter	Min	Max	Unit	Pin Numbers	Conditions
LOW Drive Output with Schmitt Trigger Input (STI)	I_{OL}	7.3	—	mA	1-4,6-8,10-16,18,20-25,27-29,32,33,35-37, 39-42,44,46-48,50,52,53,56,58-60,62-69, 71-77,82-85,87-94,96-99,101-105,167, 205-208	V_{OL} = 0.4V
	I_{OH}	-8.0	—	mA		V_{OH} = (V_{cc} I/O - 0.4)
	V_{IL}	—	0.8	V		—
	V_{IH}	2.0	(V_{cc}I/O + 0.5)	V		—
	V_{OH}	V_{cc} - 0.4	—	V		—
HIGH Drive Output with Standard Input	I_{OL}	9.4	—	mA	49,51,54,55,106-108,110,112-117,119, 121,123-128,130,132-137,139,141,143, 150,152,154-159,161,163-166,168-170, 172,174-179,181,185-190,192,194-200, 202,204	V_{OL} = 0.4V
	I_{OH}	-15	—	mA		V_{OH} = (V_{cc} I/O - 0.4)
	V_{IL}	—	0.8	V		—
	V_{IH}	2.0	(V_{cc}I/O + 0.5)	V		—
	V_{OH}	V_{cc} - 0.4	—	V		—
Clock Drive Output	I_{OL}	39	—	mA	183	V_{OL} = 0.4V
	I_{OH}	-24	—	mA		V_{OH} = (V_{cc} I/O - 0.4)
Capacitance	C_{IN}	—	10	pF	All pins	—
Leakage	I/O_{LEAK}	—	20	µA	All pins	—

Table 18 DC Electrical Characteristics

USB Electrical Characteristics

	Parameter	Min	Max	Unit	Conditions
USB Interface					
V_{di}	Differential Input Sensitivity	-0.2		V	I(D+)-(D-)I
V_{cm}	Differential Input Common Mode Range	0.8	2.5	V	
V_{se}	Single ended Receiver Threshold	0.8	2.0	V	
C_{in}	Transceiver Capacitance		20	pF	
I_{li}	Hi-Z State Data Line Leakage	-10	10	µA	$0V < V_{in} < 3.3V$
USB Upstream/Downstream Port					
V_{oh}	Static Output High	2.8	3.6	V	15km ± 5% to Gnd
V_{ol}	Static Output Low		0.3	V	
Z_o	USB Driver Output Impedance	28	44	Ω	Including $R_{ext} = 20\ \Omega$

Table 19 USB Interface Characteristics

Power Consumption

Note: This table is based on a 2:1 CPU pipeline to system (PClock to CLKP) clock ratio.

Parameter		133MHz		150MHz		180MHz		Unit	Conditions
		Typical	Max.	Typical	Max.	Typical	Max.		
I_{CC} I/O		80	130	100	150	120	170	mA	
$I_{CC\ core}$	Normal mode	400	450	450	500	500	550	mA	C_L = 25pF (affects I/O) $T_a = 25^oC$ VccP = 2.625V (for max. values) V_{cc} core = 2.625V (for max. values) V_{cc} I/O = 3.46V (for max. values) VccP = 2.5V (for typical values) V_{cc} core = 2.5V (for typical values) V_{cc} I/O = 3.3V (for typical values)
	Standby mode[1]	320	370	360	410	400	450	mA	
Power Dissipation	Normal mode	1.26	1.63	1.46	1.86	1.73	2.03	W	
	Standby mode[1]	1.06	1.42	1.22	1.59	1.47	1.77	W	

1. RISCore 32300 CPU core enters Standby mode by executing WAIT instructions; however, other logic continues to function. Standby mode reduces power consumption by 0.6 mA per MHz of the CPU pipeline clock, PClock.

Table 20 RC32355 Power Consumption

Power Curve

The following graph contains a power curve that shows power consumption at various bus frequencies.

Note: The system clock (CLKP) can be multiplied by 2, 3, or 4 to obtain the CPU pipeline clock (PClock) speed.

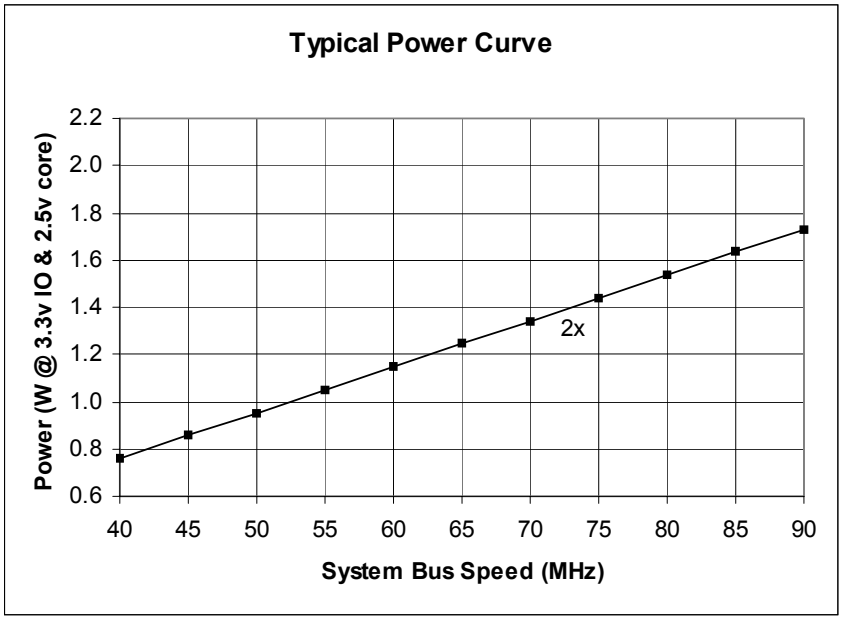


Figure 23 Typical Power Usage

Absolute Maximum Ratings

Symbol	Parameter	Min[1]	Max[1]	Unit
V_{CC}I/O	I/O Supply Voltage	-0.3	3.465	V
V_{CC}Core	Core Supply Voltage	-0.3	3.0	V
V_{CC}P	PLL Supply Voltage	-0.3	3.0	V
Vimin	Input Voltage - undershoot	-0.6	—	V
Vi	I/O Input Voltage	Gnd	V_{CC}I/O+0.6	V
Ta, Industrial	Ambient Operating Temperature	-40	85	degrees C
Tstg	Storage Temperature	-40	125	degrees C

Table 21 Absolute Maximum Ratings

1. Functional and tested operating conditions are given in Table 17. Absolute maximum ratings are stress ratings only, and functional operation at the maximums is not guaranteed. Stresses beyond those listed may affect device reliability or cause permanent damage to the device.

Package Pin-out — 208-Pin PQFP

The following table lists the pin numbers and signal names for the RC32355.

Pin	Function	Alt	Pin	Function	Alt	Pin	Function	Alt	Pin	Function	Alt
1	ATMOUTP[0]		53	JTAG_TDO		105	BGN		157	MDATA[28]	
2	ATMOUTP[1]		54	GPIOP[16]	1	106	CSN[0]		158	MDATA[13]	
3	ATMINP[02]		55	GPIOP[17]	1	107	CSN[1]		159	MDATA[29]	
4	ATMOUTP[2]		56	GPIOP[18]	1	108	CSN[2]		160	Vcc I/O	
5	Vss		57	Vss		109	Vcc I/O		161	MDATA[14]	
6	ATMOUTP[3]		58	JTAG_TCK		110	CSN[3]		162	Vss	
7	ATMINP[03]		59	GPIOP[19]	1	111	Vss		163	MDATA[30]	
8	ATMOUTP[4]		60	GPIOP[20]	1	112	OEN		164	MDATA[15]	
9	Vcc I/O		61	Vcc I/O		113	RWN		165	MDATA[31]	
10	ATMOUTP[5]		62	GPIOP[21]	1	114	BDIRN		166	CLKP	
11	ATMINP[04]		63	JTAG_TDI		115	BOEN[0]		167	WAITACKN	
12	ATMOUTP[6]		64	GPIOP[22]	1	116	BOEN[1]		168	MADDR[00]	
13	ATMOUTP[7]		65	GPIOP[23]	2	117	BWEN[0]		169	MADDR[11]	
14	ATMINP[05]		66	GPIOP[24]	1	118	Vcc I/O		170	MADDR[01]	
15	ATMOUTP[8]		67	JTAG_TMS		119	BWEN[1]		171	Vcc I/O	
16	ATMOUTP[9]		68	GPIOP[25]	2	120	Vss		172	MADDR[12]	
17	Vss		69	GPIOP[26]	1	121	BWEN[2]		173	Vss	
18	ATMINP[06]		70	Vss		122	Vcc Core		174	MADDR[02]	
19	Vcc Core		71	GPIOP[27]	1	123	BWEN[3]		175	MADDR[13]	
20	GPIOP[00]	1	72	COLDRSTN		124	MDATA[00]		176	MADDR[03]	
21	GPIOP[01]	1	73	GPIOP[28]	1	125	MDATA[16]		177	MADDR[14]	
22	ATMINP[07]		74	GPIOP[29]	1	126	MDATA[01]		178	MADDR[04]	
23	GPIOP[02]	2	75	GPIOP[30]	1	127	MDATA[17]		179	MADDR[15]	
24	GPIOP[03]	1	76	GPIOP[31]	2	128	MDATA[02]		180	Vcc I/O	
25	ATMINP[08]		77	USBCLKP		129	Vcc I/O		181	MADDR[05]	
26	Vcc I/O		78	Vcc I/O		130	MDATA[18]		182	Vcc Core	
27	GPIOP[04]	2	79	USBDN		131	Vss		183	SYSCLKP	
28	GPIOP[05]	1	80	USBDP		132	MDATA[03]		184	Vss	
29	ATMINP[09]		81	Vss		133	MDATA[19]		185	MADDR[16]	
30	VccP[1]		82	MIICRSP		134	MDATA[04]		186	MADDR[06]	
31	VssP[1]		83	MIICOLP		135	MDATA[20]		187	MADDR[17]	
32	ATMINP[10]		84	MIITXDP[0]		136	MDATA[05]		188	MADDR[07]	
33	GPIOP[06]	1	85	MIITXDP[1]		137	MDATA[21]		189	MADDR[18]	
34	Vss		86	Vcc Core		138	Vcc Core		190	MADDR[08]	

Table 22: 208-pin QFP Package Pin-Out (Part 1 of 2)

Pin	Function	Alt	Pin	Function	Alt	Pin	Function	Alt	Pin	Function	Alt
35	GPIOP[07]	1	87	MIITXDP[2]		139	MDATA[06]		191	Vcc I/O	
36	ATMINP [11]		88	MIITXDP[3]		140	Vcc I/O		192	MADDR[19]	
37	GPIOP[08]	2	89	MIITXENP		141	MDATA[22]		193	Vss	
38	Vcc Core		90	MIITXCLKP		142	Vss		194	MADDR[09]	
39	GPIOP[09]	2	91	MIITXERP		143	MDATA[07]		195	MADDR[20]	
40	GPIOP[10]	2	92	MIIRXERP		144	MDATA[23]		196	MADDR[10]	
41	GPIOP[11]	2	93	MIIRXCLKP		145	SDCLKINP		197	MADDR[21]	
42	GPIOP[12]	2	94	MIIRXDVP		146	MDATA[08]		198	CASN	
43	Vcc I/O		95	Vcc I/O		147	MDATA[24]		199	RASN	
44	GPIOP[13]	2	96	MIIRXDP[0]		148	MDATA[09]		200	SDWEN	
45	Vss		97	MIIRXDP[1]		149	MDATA[25]		201	Vcc I/O	
46	GPIOP[14]	1	98	MIIRXDP[2]		150	MDATA[10]		202	SDCSN[0]	
47	GPIOP[15]	1	99	MIIRXDP[3]		151	Vcc I/O		203	Vss	
48	GPIOP[35]	1	100	Vss		152	MDATA[26]		204	SDCSN[1]	
49	GPIOP[34]	1	101	MIIDCP		153	Vss		205	ATMINP[00]	
50	GPIOP[33]	1	102	MIIDIOP		154	MDATA[11]		206	ATMIOP[0]	
51	GPIOP[32]	1	103	RSTN		155	MDATA[27]		207	ATMIOP[1]	
52	INSTP		104	BRN		156	MDATA[12]		208	ATMINP[01]	

[1] VccP and VssP are the Phase Lock Loop (PLL) power and ground. PLL power and ground should be supplied through a special filter circuit.

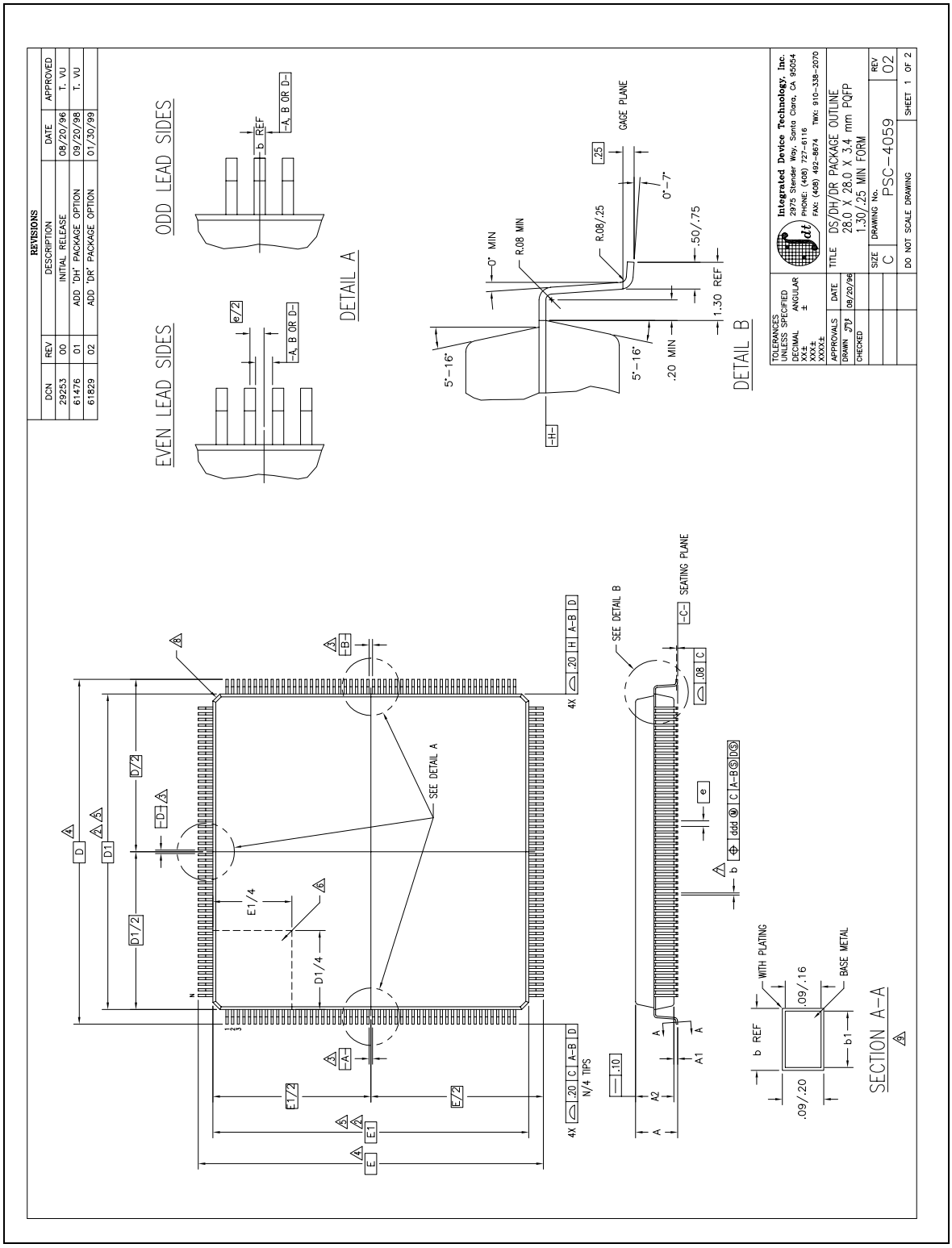
Table 22: 208-pin QFP Package Pin-Out (Part 2 of 2)

Alternate Pin Functions

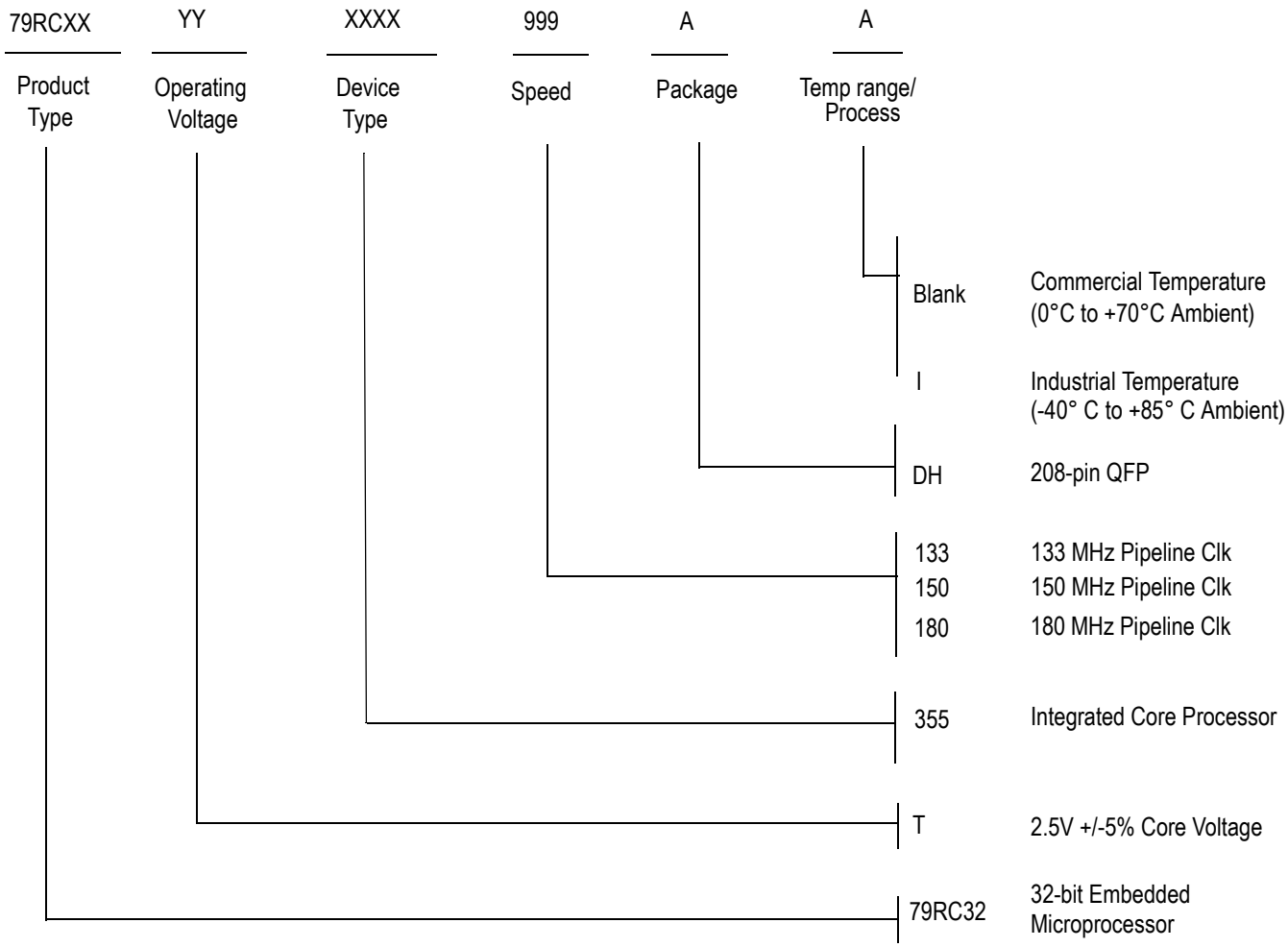
Pin	Primary	Alt #1	Alt #2	Pin	Primary	Alt #1	Alt #2
20	GPIOP[00]	U0SOUTP		51	GPIOP[32]	TDMDOP	
21	GPIOP[01]	U0SINP		54	GPIOP[16]	CSN[4]	
23	GPIOP[02]	U0RIN	JTAG_TRST_N	55	GPIOP[17]	CSN[5]	
24	GPIOP[03]	U0DCRN		56	GPIOP[18]	DMAREQN	
27	GPIOP[04]	U0DTRN	CPUP	59	GPIOP[19]	DMADONEN	
28	GPIOP[05]	U0DSRN		60	GPIOP[20]	USBSOF	
33	GPIOP[06]	U0RTSN		62	GPIOP[21]	CKENP	
35	GPIOP[07]	U0CTSN		64	GPIOP[22]	TXADDR[0]	
37	GPIOP[08]	U1SOUTP	DMAP[3]	65	GPIOP[23]	TXADDR[1]	DMAP[0]
39	GPIOP[09]	U1SINP	DMAP[2]	66	GPIOP[24]	RXADDR[0]	
40	GPIOP[10]	U1DTRN	EJTAG_PCST[0]	68	GPIOP[25]	RXADDR[1]	DMAP[1]
41	GPIOP[11]	U1DSRN	EJTAG_PCST[1]	69	GPIOP[26]	TDMTEN	
42	GPIOP[12]	U1RTSN	EJTAG_PCST[2]	71	GPIOP[27]	MADDR[22]	
44	GPIOP[13]	U1CTSN	EJTAG_DCLK	73	GPIOP[28]	MADDR[23]	
46	GPIOP[14]	SDAP		74	GPIOP[29]	MADDR[24]	
47	GPIOP[15]	SCLP		75	GPIOP[30]	MADDR[25]	
48	GPIOP[35]	TDMCLKP		76	GPIOP[31]	DMAFIN	EJTAG_TRST_N
49	GPIOP[34]	TDMFP					
50	GPIOP[33]	TDMDIP					

Table 23 Alternate Pin Functions

Package Drawing - 208-pin QFP



Ordering Information



Valid Combinations

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79RC32T355 -133DHI, 150DHI	208-pin QFP package, Industrial Temperature

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